



Title of Change:	Assembly site transfer of Ball Grid Array (BGA) from J-Device Kitakami to J-Device Kitsuki.		
Proposed first ship date:	3 September 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or <Fumio.Baba@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office		
Type of notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.</p> <p>ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.</p>		
Change Part Identification:	Affected products will be identified with marking lot number and ASSY LOC CODE "J1" in MPN Label		
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change	<input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) :	<input checked="" type="checkbox"/> External Foundry/Subcon site(s) J-Devices Corporation	
Description and Purpose:			
<p>This is the Final Notification to announce the plan to transfer the assembly site of Ball Grid Array (BGA) products from J-Device Kitakami to J-Device Kitsuki. The assembly site of Ball Grid Array (BGA) will move from J-Device Kitakami to J-Device Kitsuki, Japan.</p> <p>The current material used, process flow, process control and product specification such as visual, physical dimension, electrical characteristic remain the same.</p> <p>Note: Current test site for the affected products doesn't change.</p>			



Reliability Data Summary:

QV DEVICE NAME: LC823425-13W1-E

PACKAGE: FBGA221

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008hrs	0/150
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/90
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/300
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/90
THB	JESD22-A101	85°C, 85% RH, bias	1008 hrs	0/90
AC	JESD22-A102	121°C, 100% RH, 15psig, unbiased	192hrs	0/90
SAT				0/30
PUD	12MON49370E	After TC 500c		0/5
SD	JSTD002	Ta = 245C, 10 sec		0/ 9

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
LC823425-13W1-E	LC823425-13W1-E
LC823425-13W1-LR-E	LC823425-13W1-E
LC823425-14S1-E	LC823425-13W1-E